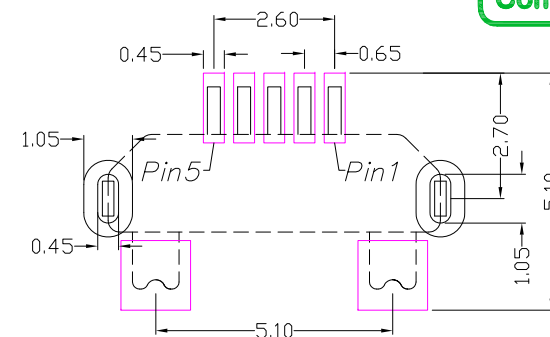
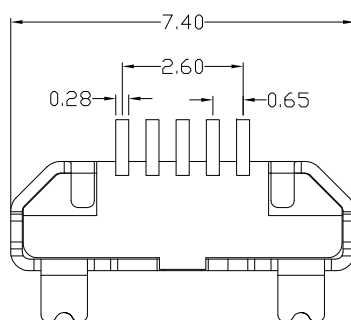
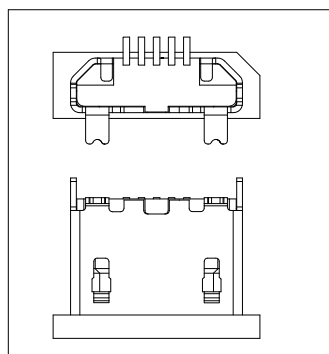
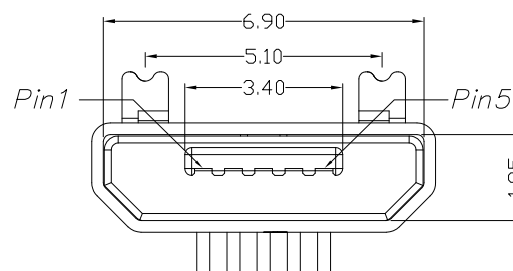
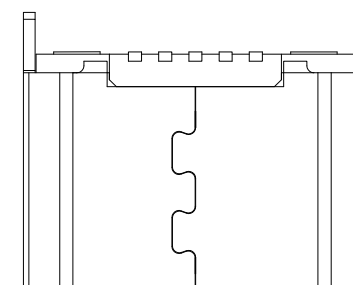
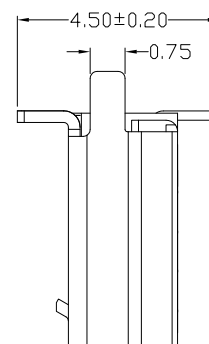
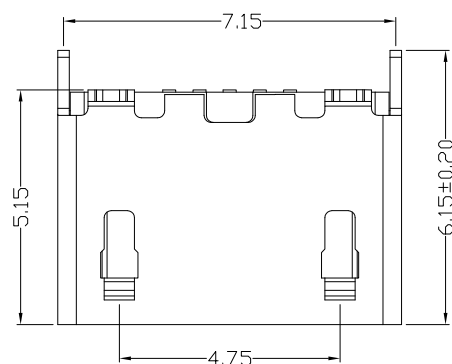
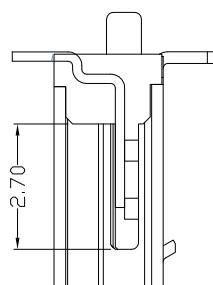




PCB LAYOUT MOUNTING PATTERN



NOTES:t

MATERIAL:

1.1 HOUSING: LCP / PA9T

1.2 CONTACT: PHOSPHOR BRONZE

1.3 SHELL: SUS

Finish:

2.1 Contact: Plated Gold in Mating Area ;

Gold Plated on Solder Balls

Nickel under plated overall

2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

3.1 CURRENT RATING: 1.0A

3.2 DIELECTRIC WITHSSTANDING VOLTAGE: 100 V(ac) FOR 1min

3.3 CONTACT RESISTANCE: 30 mΩ MAX.

3.4 INSULATION RESISTANCE: 100 MΩ MIN.

3.5 TOTAL MATING FORCE: 3.57 Kgf MAX.

3.6 TOTAL UNMATING FORCE: 1.0 Kgf MIN.

3.7 TEMPERATURE RANGE: -30°C ~ +80°C



东莞市高迪电子有限公司

Dong Guan KDDR Electronic Switch Jack Co., Ltd.

TOLERANCE UNLESS
OTHERWISE STATED :

Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3°

3RD.
ANGEL'S



UNITS

MM

DRAWN BY: Jack Lu
DATE: 04/24/20

CHECKED BY: Jacky Chen
DATE: 04/24/20

APPROVED BY: Tony Kao
DATE: 04/24/20

MAT'L	TITLE	CONNECTOR
FINISH	MODLE	MICRO USB 5P 直立式SMT ,無捲邊
SCALE	DWG NO.	MRUSB-5B-VS7NI-S306
SHEET NO.	PART NO.	MRUSB-5B-VS7NI-S306

ITEM NO	DESCRIPTION	DRAWN	DATE
6	更新外觀鍍線	Jack	042420
5	更新尺寸	Jack	030220
4	新增PIN編號	Jack	050319
3	更新圖面	Jack	042619
2	新增PCB LAYOUT尺寸	Jack	010319
1	更新為A0版	Jack	041718